

FEATURES

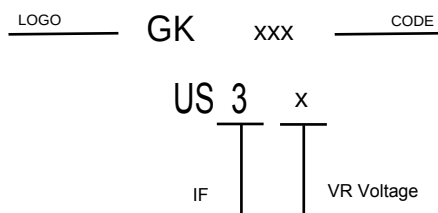
- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Fast switching speed

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Metallurgically bonded construction
- * Polarity: Color band denotes cathode end
- * Mounting position: Any
- * Weight: 0.093 grams



VOLTAGE RANGE
50 to 1000 Volts
CURRENT
3.0 Ampere



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	US3A	US3B	US3D	US3E	US3G	US3J	US3K	US3M	UNITS
Maximum Recurrent Peak Reverse Voltage	50	100	200	300	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	210	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	300	400	600	800	1000	V
Maximum Average Forward Rectified Current	3.0								A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	100								A
Maximum Instantaneous Forward Voltage at 3.0A	1.0			1.3		1.85			V
Maximum DC Reverse Current Ta=25°C	10								μA
at Rated DC Blocking Voltage Ta=100°C	200								μA
Maximum Reverse Recovery Time (Note 1)	50					75			nS
Typical Junction Capacitance (Note 2)	75								pF
Operating and Storage Temperature Range Tj, Tstg	-65 — +150								°C

NOTES:

1. Reverse Recovery Time test condition: IF=0.5A, IR=1.0A, IRR=0.25A
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

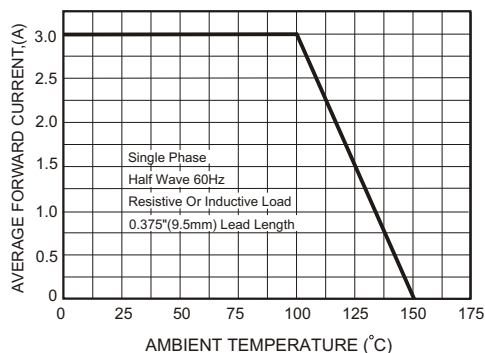
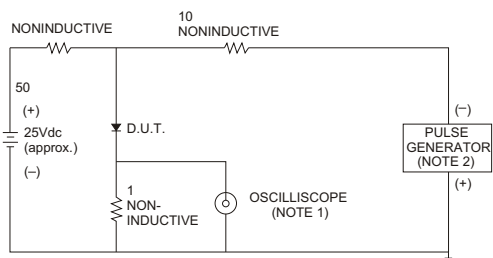


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm, 22pF.

2. Rise Time= 10ns max., Source Impedance= 50 ohms.

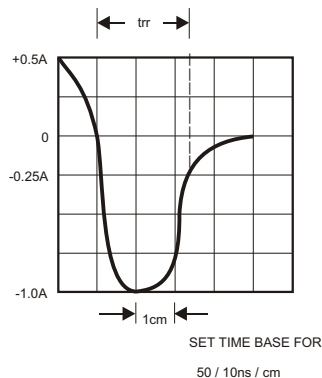


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

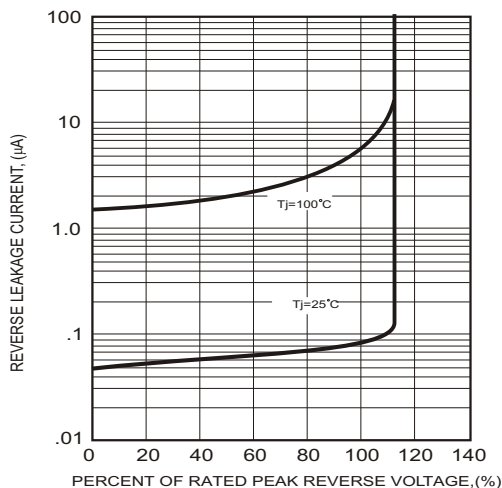


FIG.2-TYPICAL FORWARD CHARACTERISTICS

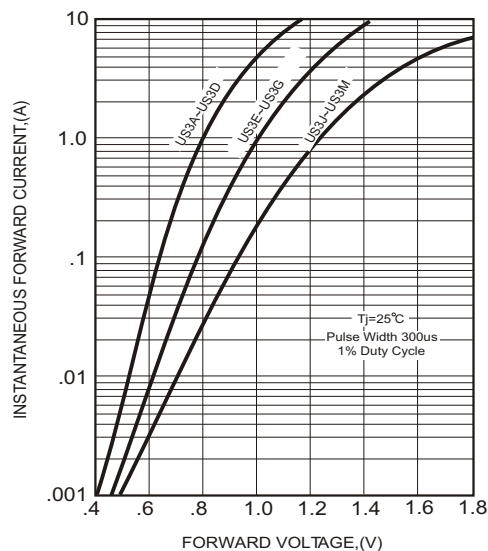


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

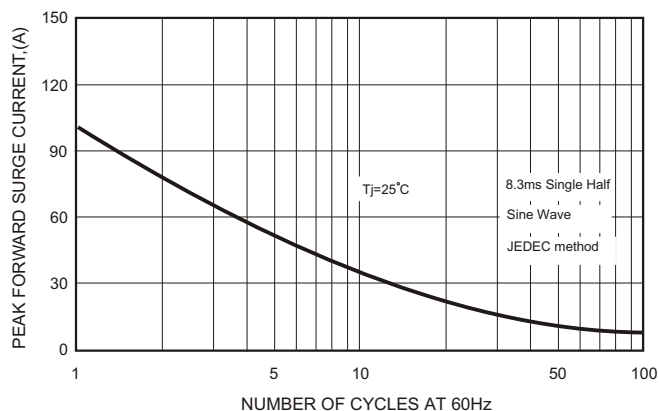
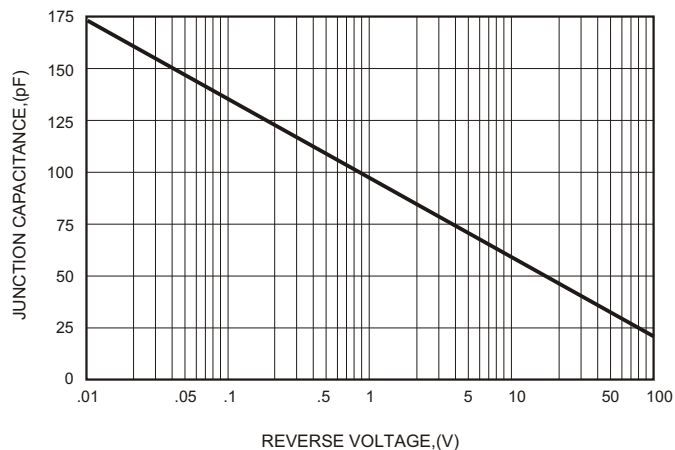


FIG.6-TYPICAL JUNCTION CAPACITANCE



Soldering parameters

FIG5: Reflow condition

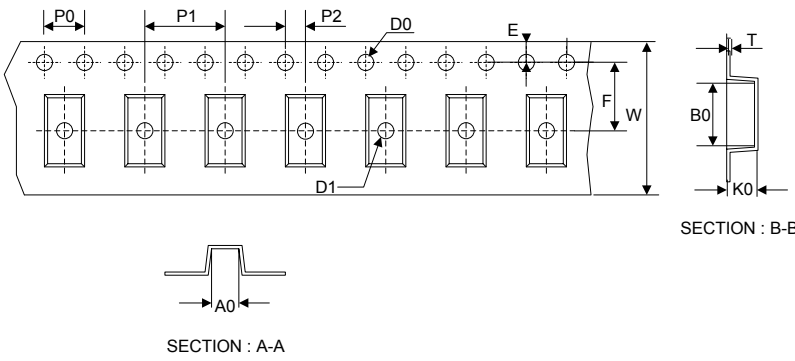
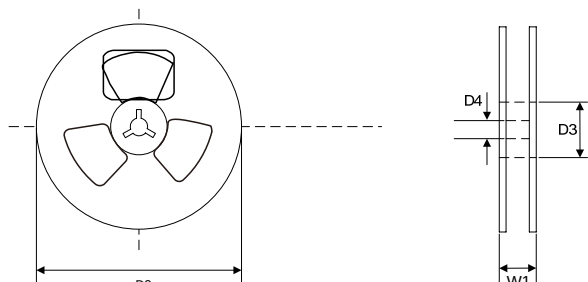
The graph illustrates the temperature profile for a reflow condition. The y-axis represents Temperature (°C) and the x-axis represents Time. The profile starts at a preheat temperature, ramps up to a peak temperature, and then ramps down. Key parameters labeled include: T_P (Peak Temperature), T_L (Liquidus Temperature), $T_{S(max)}$ (Maximum Soldering Temperature), $T_{S(min)}$ (Minimum Soldering Temperature), t_s (Time to peak temperature), t (Time in the critical zone), and t_p (Time at peak temperature). The critical zone is defined between T_L and T_P . The preheat region is shaded gray, and the critical zone is also shaded gray.

Package Dimensions & Suggested Pad Layout

Technical drawing of a rectangular box. The top view shows a rectangle with width B and height A . The side view shows a rectangle with width E and height J . The depth of the box is C . The height of the top flange is D . The height of the bottom flange is G . The width of the bottom flange is H .

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Tape & reel specification

Tape		Symbol	Dimension (mm)
 SECTION : A-A SECTION : B-B		P0	4.00±0.20
		P1	8.00±0.20
		P2	2.00±0.20
		D0	1.60±0.20
		D1	1.60±0.20
		E	1.75±0.20
		F	5.50±0.15
		W	12.00±0.20
		A0	4.00±0.20
		B0	5.45±0.20
		K0	2.50±0.25
		T	0.20±0.10
		D2	330.0±5.0
		D3	73.0Min.
		D4	14.0±2.5
13" Reel		W1	16.0±2.5
		Quantity: 3000PCS	